

ABSTRACT

A solderable flexible adhesive interposer having solderable contacts includes low-modulus-of-elasticity (i.e. molecularly flexible) conductive adhesive vias to which contacts of an electronic device, such as a semiconductor chip or die or other component, are connected. The flexible adhesive interposer substrate includes a sheet or layer of a molecularly flexible dielectric adhesive having via holes therein through which the flexible conductive adhesive vias reside. A thin layer of solderable metal, preferably a plating of gold or nickel-gold, on at least one exposed surface of the flexible conductive adhesive vias provides the solderable contacts connecting electrically to the conductive vias. The electronic device may be covered by a lid or by an encapsulant attached to the flexible adhesive interposer substrate and/or the electronic device.

[illegible]